

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)	Attorney Docket No.: MIYOSH0008
)	
Seiichi AKAGI et al.)	Confirmation No.: 6701
)	
Serial No.: 10/598,515)	Group Art Unit: 1796
)	
Filed: September 1, 2006)	Examiner: Hannah J. PAK
)	
For: SEALANT EPOXY-RESIN MOLDING)	Date: February 22, 2010
MATERIAL, AND ELECTRONIC)	
COMPONENT DEVICE)	

AMENDMENT (D)

MAIL STOP: AMENDMENT
U.S. Patent and Trademark Office
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Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In response to the non-final Office Action mailed August 21, 2009, please enter the following remarks in the application identified above:

Amendments to the Claims are reflected by the Listing of Claims that begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.